

Abstract

The present invention provides an electrodeposited copper foil which solves problems of electrodeposited-copper-clad laminates to which the foil has been incorporated, such as bow, twist, and poor dimensional stability, and a method of inspecting an electrodeposited copper foil so as to assure the quality of the foil. In the invention, there is employed an electrodeposited copper foil which recrystallizes by heating at low temperature during production of a copper-clad laminate employing an electrodeposited copper foil and which exhibits an elongation as high as 18% or more in an atmosphere of 180°C, wherein the maximum rate of decrease in maximum tensile strength falls within the aging time ranging from 5 to 10 minutes in a process in which tensile strength decreases as time elapses during aging in an atmosphere at 170°C, and the change in tensile strength in a knick portion shown in a {tensile strength} vs. {aging time} curve which is drawn in an x-y plane and which has a knick portion is 3 kg/mm² or more, the x-axis representing aging time and the y-axis representing tensile strength.